

MULTI-BEAM

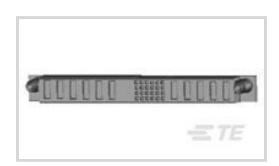
TE Internal #: 6450140-9

PCB Mount Receptacle, Vertical, Board-to-Board, 35 Position, 2.54 mm / 6.35 mm [.1 in / .25 in] Centerline, Fully Shrouded, Gold

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: **35**Number of Rows: **4**

Features

Electrical Characteristics

Operating Voltage	200 VDC, 60 VDC
Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]
Connector Width	11.94 mm[.47 in]
PCB Thickness (Recommended)	2.11 – 2.62 mm[.083 – .103 in]
Connector Height	12.7 mm[.5 in]
Connector Length	110.49 mm[4.35 in]
Packaging Features	
Packaging Quantity	22
Packaging Method	Tray
Industry Standards	
Glow Wire Rating	High Temperature Part - Not Glow Wire
UL Flammability Rating	UL 94V-0
Usage Conditions	
Operating Temperature (Max)	105 °C[221 °F]

-55 – 105 °C[-67 – 221 °F]

Without

Operating Temperature Range

Mechanical Attachment

Mating Retention



PCB Mount Alignment Type Hold Down PCB Mount Alignment Type Hold-Down PCB Mount Retention With PCB Mount Alignment With Connector Mounting Type Board Mount Mating Alignment With Termination Features With Termination Post & Tail Length 3.43 mm,L135 in] Termination Method to PCB Through Hole Solder Contact Features Through Hole Solder Contact Underplaining Material Nickel Contact Underplaining Material Thickness 1.27 - 2.54 µm,[50 - 100 µin] Contact Moting Area Plating Material Thickness 0.76 µm,[3 µin] PCB Contact Termination Area Plating Material Thickness 2.54 - 5.06 µm,[100 - 200 µin] Contact Basis Material Copper Alloy PCB Contact Termination Area Plating Material In Contact Mating Area Plating Material Gold Contact Mating Area Plating Material Gold Contact Type Receptacle Contact Type Receptacle Contact Type Receptacle Contact Type Receptacle <t< th=""><th>Mating Alignment Type</th><th>Guide Post</th></t<>	Mating Alignment Type	Guide Post
PCB Mount Retention With PCB Mount Alignment With Connector Mounting Type Board Mount Mating Alignment With Termination Features Termination Peatures Termination Peatures Termination Method to PCB Through Hole - Soider Contact Peatures Contact Underplating Material Contact Underplating Material Thickness 1,27 – 2,54 µml50 – 100 µml Contact Underplating Material Thickness 0,76 µml3 µml PCB Contact Termination Area Plating Material Thickness 2,54 – 5,08 µml100 – 200 µml Contact Mating Area Plating Material Thickness 2,554 – 5,08 µml100 – 200 µml Contact Layout Matrix Contact Base Material Contact Base Material PCB Contact Termination Area Plating Material FCB Contact Termination Area Plating Material Gold Contact Mating Area Plating Material Gold Contact Type Receptable Contact Current Rating (Max) 42 A Housing Features Housing Material High Temperature Thermoplastic Glass Filled Centerline (Pitch) 6,35 mm, 2,54 mmi (25 in)l.1 in) Configuration Features Number of Columns 17 Number of Signal Positions 35 Number of Signal Positions 11 PCB Mount Orientation Vertical Number of Power Positions 11 PCB Mount Orientation Vertical Number of Positions 35	PCB Mount Retention Type	Hold-Down
PCB Mount Alignment With Connector Mounting Type Board Mount Mating Alignment With Termination Features Termination Post & Tail Length 3.43 mm [135 in] Termination Method to PCB Through Hole Solder Contact Features Contact Features Contact Underplating Material Mickels 1.27 – 2.54 pm [50 – 100 pin] Contact Underplating Material Thickness 1.27 – 2.54 pm [50 – 100 pin] Contact Mating Area Plating Material Thickness	PCB Mount Alignment Type	Hold-Down
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Mating Alignment Termination Features Termination Post & Tail Length Tarmination Method to PCB Through Hole - Solder Contact Features Contact Features Contact Underplating Material Contact Underplating Material Thickness 1,27 - 2,54 µm[50 - 100 µin] Contact Mating Area Plating Material Thickness PCB Contact Termination Area Plating Material Thin Contact Base Material PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Gold Contact Mating Area Plating Material Gold Contact Type Receptable Contact Current Rating (Max) 42 A Housing Features Housing Material High Temperature Thermoplastic Glass-Filled Centerline (Pitch) 6.35 mm, 2.54 mm/ 25 in][.1 in] Configuration Features Number of Columns 17 Number of Signal Positions 18 Number of Signal Positions 19 Number of Power Positions 11 PCB Mount Orientation Vertical Number of Positions 35	PCB Mount Alignment	With
Termination Features Termination Post & Tail Length 3.43 mm[.135 in] Termination Method to PCB Through Hole - Solder Contact Features Contact Underplating Material Nickel Contact Underplating Material Thickness 1.27 - 2.54 µm[50 - 100 µin] Contact Mating Area Plating Material Thickness .076 µm[3 µin] PCB Contact Termination Area Plating Material Thickness .2.54 - 5.08 µm[100 - 200 µin] Contact Base Material Copper Alloy PCB Contact Termination Area Plating Material Thickness .7 in Copper Alloy PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material .7 in .7 in Contact Mating Area Plating Material .7 in Contact Type .8 ecceptacle Contact Current Rating (Max) .42 A Housing Features Housing Material .1 ligh Temperature Thermoplastic Glass-Filled Centerline (Pitch) .6.35 mm, 2.54 mm[.25 in][.1 in] Configuration Features Number of Columns .17 Number of Signal Positions .24 Number of Signal Positions .24 Number of Power Positions .11 PCB Mount Orientation Vertical Number of Positions .35	Connector Mounting Type	Board Mount
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Termination Method to PCB Contact Features Contact Underplating Material Contact Underplating Material Thickness 1.27 - 2.54 \munipmode mild ping Material Thickness 1.27 - 2.54 \munipmode mild ping Material Thickness Contact Mating Area Plating Material Thickness PCB Contact Termination Area Plating Material Thickness Contact Layout Matrix Contact Basic Material Copper Alloy PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Contact Mating Area Plating Material Gold Contact Type Receptacle Contact Current Rating (Max) Housing Features Housing Material High Temperature Thermoplastic Glass Filled Centerline (Pitch) 6.35 mm, 2.54 mm[.25 in][.1 in] Configuration Features Number of Columns Number of Signal Positions Number of Power Positions 11 PCB Mount Orientation Vertical Number of Positions 35	Termination Features	
Contact Underplating Material Contact Underplating Material Thickness 1.27 – 2.54 µm[50 – 100 µin] Contact Underplating Material Thickness 0.076 µm[3 µin] PCB Contact Termination Area Plating Material Thickness 2.54 – 5.08 µm[100 – 200 µin] Contact Layout Matrix Contact Base Material Copper Alloy PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Gold Contact Type Receptacle Contact Current Rating (Max) 42 A Housing Features Housing Material High Temperature Thermoplastic Glass-Filled Centerline (Pitch) 6.35 mm, 2.54 mm[25 in][.1 in] Configuration Features Number of Columns Number of Signal Positions Number of Positions 11 PCB Mount Orientation Vertical Number of Positions 35	Termination Post & Tail Length	3.43 mm[.135 in]
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Contact Underplating Material Thickness 1.27 – 2.54 µm[50 – 100 µin] Contact Mating Area Plating Material Thickness .076 µm[3 µin] PCB Contact Termination Area Plating Material Thickness 2.54 – 5.08 µm[100 – 200 µin] Contact Layout Matrix Contact Base Material Copper Alloy PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Gold Contact Mating Area Plating Material Gold Contact Type Receptacle Contact Current Rating (Max) 42 A Housing Features Housing Material High Temperature Thermoplastic Glass-Filled Centerline (Pitch) 6.35 mm, 2.54 mm[.25 in][.1 in] Configuration Features Number of Columns 17 Number of Loaded Positions 35 Number of Signal Positions 11 PCB Mount Orientation Vertical Number of Positions 35	Contact Features	
Contact Mating Area Plating Material Thickness .076 µm[3 µin] PCB Contact Termination Area Plating Material Thickness 2.54 – 5.08 µm[100 – 200 µin] Contact Layout Matrix Contact Base Material Copper Alloy PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Gold Contact Type Receptacle Contact Current Rating (Max) 42 A Housing Features Housing Material High Temperature Thermoplastic Glass-Filled Centerline (Pitch) 6.35 mm, 2.54 mm[.25 in][.1 in] Configuration Features Number of Columns 17 Number of Signal Positions 24 Number of Power Positions 11 PCB Mount Orientation Vertical Number of Positions 35	Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material Thickness Contact Layout Matrix Contact Base Material Copper Alloy PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Contact Type Receptacle Contact Current Rating (Max) Housing Features Housing Material High Temperature Thermoplastic Glass-Filled Centerline (Pitch) Configuration Features Number of Columns Number of Signal Positions Number of Power Positions 11 PCB Mount Orientation Number of Positions 35 Number of Positions 36 Number of Positions 37 Number of Positions 38 Number of Positions 39 Number of Positions 30 Number of Positions 31 PCB Mount Orientation Vertical	Contact Underplating Material Thickness	1.27 – 2.54 μm[50 – 100 μin]
Contact Layout Matrix Contact Base Material Copper Alloy PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Gold Contact Type Receptacle Contact Current Rating (Max) 42 A Housing Features Housing Material High Temperature Thermoplastic Glass-Filled Centerline (Pitch) 6.35 mm, 2.54 mm[.25 in][.1 in] Configuration Features Number of Columns 17 Number of Signal Positions 35 Number of Power Positions 11 PCB Mount Orientation Vertical Number of Positions 35	Contact Mating Area Plating Material Thickness	.076 μm[3 μin]
Contact Base Material Copper Alloy PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Gold Contact Type Receptacle Contact Current Rating (Max) 42 A Housing Features Housing Material High Temperature Thermoplastic Glass-Filled Centerline (Pitch) 6.35 mm, 2.54 mm[.25 in][.1 in] Configuration Features Number of Columns 17 Number of Loaded Positions 35 Number of Signal Positions 24 Number of Power Positions 11 PCB Mount Orientation Vertical Number of Positions 35	PCB Contact Termination Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]
PCB Contact Termination Area Plating Material Contact Mating Area Plating Material Contact Type Receptacle Contact Current Rating (Max) Housing Features Housing Material High Temperature Thermoplastic Glass Filled Centerline (Pitch) 6.35 mm, 2.54 mm[.25 in][.1 in] Configuration Features Number of Columns Number of Loaded Positions Number of Signal Positions 11 PCB Mount Orientation Vertical Number of Positions 35	Contact Layout	Matrix
Contact Mating Area Plating Material Contact Type Receptacle Contact Current Rating (Max) Housing Features Housing Material High Temperature Thermoplastic Glass-Filled Centerline (Pitch) 6.35 mm, 2.54 mm[.25 in][.1 in] Configuration Features Number of Columns 17 Number of Loaded Positions 35 Number of Signal Positions 24 Number of Power Positions 11 PCB Mount Orientation Vertical Number of Positions 35	Contact Base Material	Copper Alloy
Contact Type Receptacle Contact Current Rating (Max) 42 A Housing Features Housing Material High Temperature Thermoplastic Glass-Filled Centerline (Pitch) 6.35 mm, 2.54 mm[.25 in][.1 in] Configuration Features Number of Columns 17 Number of Loaded Positions 35 Number of Signal Positions 24 Number of Power Positions 11 PCB Mount Orientation Vertical Number of Positions 35	PCB Contact Termination Area Plating Material	Tin
Contact Current Rating (Max) Housing Features Housing Material High Temperature Thermoplastic Glass-Filled Centerline (Pitch) 6.35 mm, 2.54 mm[.25 in][.1 in] Configuration Features Number of Columns 17 Number of Loaded Positions 35 Number of Signal Positions 24 Number of Power Positions 11 PCB Mount Orientation Number of Positions 35	Contact Mating Area Plating Material	Gold
Housing Features Housing Material High Temperature Thermoplastic Glass-Filled Centerline (Pitch) 6.35 mm, 2.54 mm[.25 in][.1 in] Configuration Features Number of Columns 17 Number of Loaded Positions 35 Number of Signal Positions 24 Number of Power Positions 11 PCB Mount Orientation Vertical Number of Positions 35	Contact Type	Receptacle
Housing Material High Temperature Thermoplastic Glass-Filled Centerline (Pitch) 6.35 mm, 2.54 mm[.25 in][.1 in] Configuration Features Number of Columns 17 Number of Loaded Positions 35 Number of Signal Positions 24 Number of Power Positions 11 PCB Mount Orientation Vertical Number of Positions 35	Contact Current Rating (Max)	42 A
Centerline (Pitch) 6.35 mm, 2.54 mm[.25 in][.1 in] Configuration Features Number of Columns 17 Number of Loaded Positions 35 Number of Signal Positions 24 Number of Power Positions 11 PCB Mount Orientation Vertical Number of Positions 35	Housing Features	
Configuration FeaturesNumber of Columns17Number of Loaded Positions35Number of Signal Positions24Number of Power Positions11PCB Mount OrientationVerticalNumber of Positions35	Housing Material	
Number of Columns17Number of Loaded Positions35Number of Signal Positions24Number of Power Positions11PCB Mount OrientationVerticalNumber of Positions35	Centerline (Pitch)	6.35 mm, 2.54 mm[.25 in][.1 in]
Number of Loaded Positions35Number of Signal Positions24Number of Power Positions11PCB Mount OrientationVerticalNumber of Positions35	Configuration Features	
Number of Signal Positions24Number of Power Positions11PCB Mount OrientationVerticalNumber of Positions35	Number of Columns	17
Number of Power Positions11PCB Mount OrientationVerticalNumber of Positions35	Number of Loaded Positions	35
PCB Mount Orientation Vertical Number of Positions 35	Number of Signal Positions	24
Number of Positions 35	Number of Power Positions	11
	PCB Mount Orientation	Vertical
Number of Rows 4	Number of Positions	35
	Number of Rows	4



Product Type Features

Mixed & Hybrid Header	Yes
Connector Shape	Rectangular
PCB Connector Assembly Type	PCB Mount Receptacle
Connector System	Board-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Body Features	
Primary Product Color	Black
Operation/Application	
Circuit Application	Power & Signal
Other	
EU RoHS Compliance	Compliant

Compliant

Product Compliance

EU ELV Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous



materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Compatible Parts



Customers Also Bought



















TE Part #1-1734346-1 STD USB TYPE B, R/A, SMT



291-0170-00100B=TA CONN,PIN





Documents

Product Drawings MBXL VERT RCPT 5P+24S+1M+6P



English

CAD Files

Customer View Model

ENG_CVM_CVM_6450140-9_D.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_6450140-9_D.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_6450140-9_D.3d_stp.zip

English

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Datasheets & Catalog Pages

2_PIECE_POWER_CONNECTORS_qrg_4-1773458-1

English

Product Specifications

Application Specification

English